2.0x1.25mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APHBM2012LSURKZGKC

Hyper Red Green

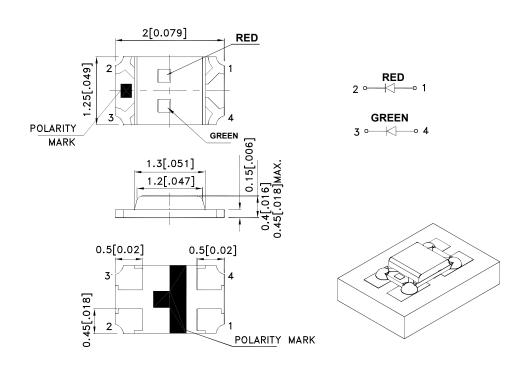
Features

- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Bi -color, low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with Al GaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



SPEC NO: DSAO4526

APPROVED: Wynec

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHBM2012LSURKZGKC	Hyper Red (AlGaInP)	- Water Clear	10	20	- 120°
			*2	*10	
	Green (InGaN)		50	90	
			*50	*90	

- Notes:
 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Min.	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red Green		645 515		nm	IF=2mA	
λD [1]	Dominant Wavelength	Hyper Red Green		630 525		nm	IF=2mA	
Δλ1/2	Spectral Line Half-width	Hyper Red Green		28 35		nm	IF=2mA	
С	Capacitance	Hyper Red Green		35 45		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red Green	1.5 2.2	1.75 2.65	2.1 3.1	V	IF=2mA	
lr	Reverse Current	Hyper Red Green			10 50	uA	VR = 5V	

Notes:

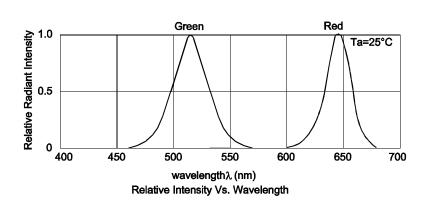
- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

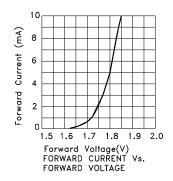
Parameter	Hyper Red	Green	Units		
Power dissipation	63	77.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage	5				
Electrostatic Discharge Threshold (HBM)	3000	450			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

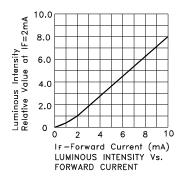
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

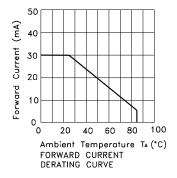
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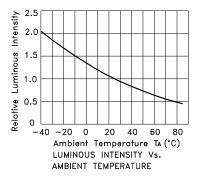


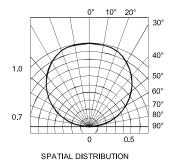
APHBM2012LSURKZGKC Hyper Red







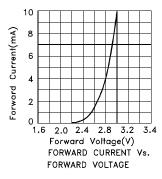


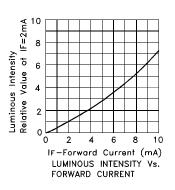


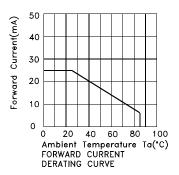
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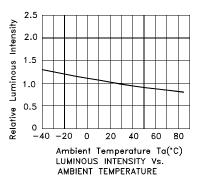
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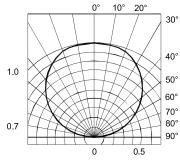
Green











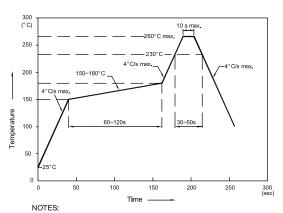
SPATIAL DISTRIBUTION

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



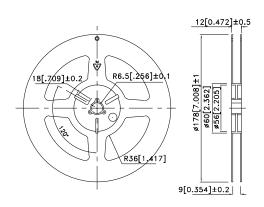
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed $% \left(1\right) =\left(1\right) \left(1\right)$
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

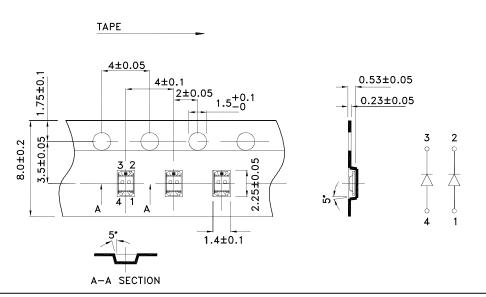
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

Tape Dimensions

(Units: mm)

Reel Dimension



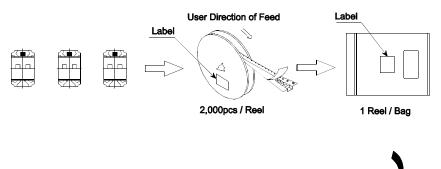


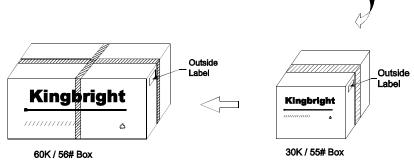
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PACKING & LABEL SPECIFICATIONS

APHBM2012LSURKZGKC







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